mXT640UD-CCU001 1.0

maXTouch 640-node Touchscreen Controller Product Brief

Description

The mXT640UD-CCU001 1.0 uses a unique charge-transfer acquisition engine to implement Microchip's patented capacitive sensing method. Coupled with a state-of-the-art CPU, the entire touchscreen sensing solution can measure, classify and track a number of individual finger touches with a high degree of accuracy in the shortest response time. The mXT640UD-CCU001 1.0 allows for both mutual and self capacitance measurements, with the self capacitance measurements being used to augment the mutual capacitance measurements to produce reliable touch information.

maXTouch® Adaptive Sensing Technology

- Up to 32 X (transmit) lines and 20 Y (receive) lines for use by a touchscreen and/or key array
- A maximum of 640 nodes can be allocated to the touch sensor
- Touchscreen size of 9.7 inches (16:10 aspect ratio), assuming a sensor electrode pitch of 6.5 mm. Other sizes are possible with different electrode pitches and appropriate sensor material
- Multiple touch support with up to 16 concurrent touches tracked in real time

Keys

- Up to 32 nodes can be allocated as mutual capacitance sensor keys in addition to the touchscreen, defined as 1 key array (subject to availability of X and Y lines and other configurations)
- Support for up to 3 mutual capacitance Generic Keys as an alternative to the touchscreen key array (subject to other configurations)
- Adjacent Key Suppression (AKS) technology is supported for false key touch prevention

Touch Sensor Technology

- Discrete/out-cell support including glass and PET film-based sensors
- On-cell/touch-on display support including TFT, LCD (ITPS, IPS) and OLED
- Synchronization with display refresh timing capability
- Support for standard (for example, Diamond) and proprietary sensor patterns (review of designs by Microchip or a Microchip-qualified touch sensor module partner is recommended)

Front Panel Material and Design

- Works with PET or glass, including curved profiles (configuration and stack-up to be approved by Microchip or a Microchip-qualified touch sensor module partner)
- 10 mm glass (or 5 mm PMMA) with bare finger (dependent on sensor size, touch size, configuration and stack-up)
- 6 mm glass (or 3 mm PMMA) with multi-finger 5 mm glove (2.7 mm PMMA equivalent) (dependent on sensor size, touch size, configuration and stack-up)
- Support for non-rectangular sensor designs (for example, circular, rounded or with cutouts)

Touch Performance

- Moisture/Water Compensation
  - No false touch with condensation or water drop up to 22 mm diameter
  - One-finger tracking with condensation or water drop up to 22 mm diameter
- Mutual capacitance and self capacitance measurements supported for robust touch detection
- P2P mutual capacitance measurements supported for extra sensitive multi-touch sensing
- Noise suppression technology to combat ambient and power-line noise
  - Up to 240 V_{PP} between 1 Hz and 1 kHz sinusoidal waveform (no touches)
  - IEC 61000-4-6, 10 Vrms, Class A (normal touch operation) conducted noise immunity
- Stylus Support
  - Supports passive stylus with 1.5 mm contact diameter, subject to configuration, stack-up, and sensor design
- Burst Frequency
  - Flexible and dynamic Tx burst frequency selection to reduce EMC disturbance
  - Configurable Tx waveform shaping to reduce emissions

- Scan Speed
  - Typical report rate for 10 touches ≥100 Hz (subject to configuration)
  - Initial touch latency <20 ms for first touch from idle (subject to configuration)
  - Configurable to allow for power and speed optimization
- Touch panel failure detection
  - Automatic touch sensor diagnostics during run time to support the implementation of safety critical features
  - Diagnostics reported using dedicated output pin or by standard Object Protocol messages
  - Configurable test limits

On-chip Gestures

- Reports one-touch and two-touch gestures

Enhanced Algorithms

- Lens bending algorithms to remove display noise
- Touch suppression algorithms to remove unintentional large touches, such as palm
- Palm Recovery Algorithm for quick restoration to normal state

Data Store

- 32-byte CRC-checksummed data area for use as a run-time Product Data Store Area
- Up to 64 bytes of user's custom data (not CRC checksummed)

Power Saving

- Programmable timeout for automatic transition from Active to Idle state
- Pipelined analog sensing detection and digital processing to optimize system power efficiency

Application Interfaces

- Client interface for main communication with the device. Can be one of:
  - I^2C interface, with support for Standard mode (up to 100 kHz), Fast mode (up to 400 kHz), Fast-mode Plus (up to 1 MHz), High Speed mode (up to 3.4 MHz)
  - HID-I^2C interface for Microsoft Windows 8.x and later versions
- Interrupt to indicate when a message is available
- Additional Hardware Debug Interface to read the raw data for tuning and debugging purposes

Power Supply

- Digital (Vdd) 3.3V nominal
- Digital I/O (VddIO) 3.3V nominal
- Analog (AVdd) 3.3V nominal
- High voltage internal X line drive (XVdd) 6.6V or 9.9V with internal voltage pump

Package

- 88-ball UFBGA 6 × 6 × 0.6 mm, 0.5 mm pitch

Operating Temperature

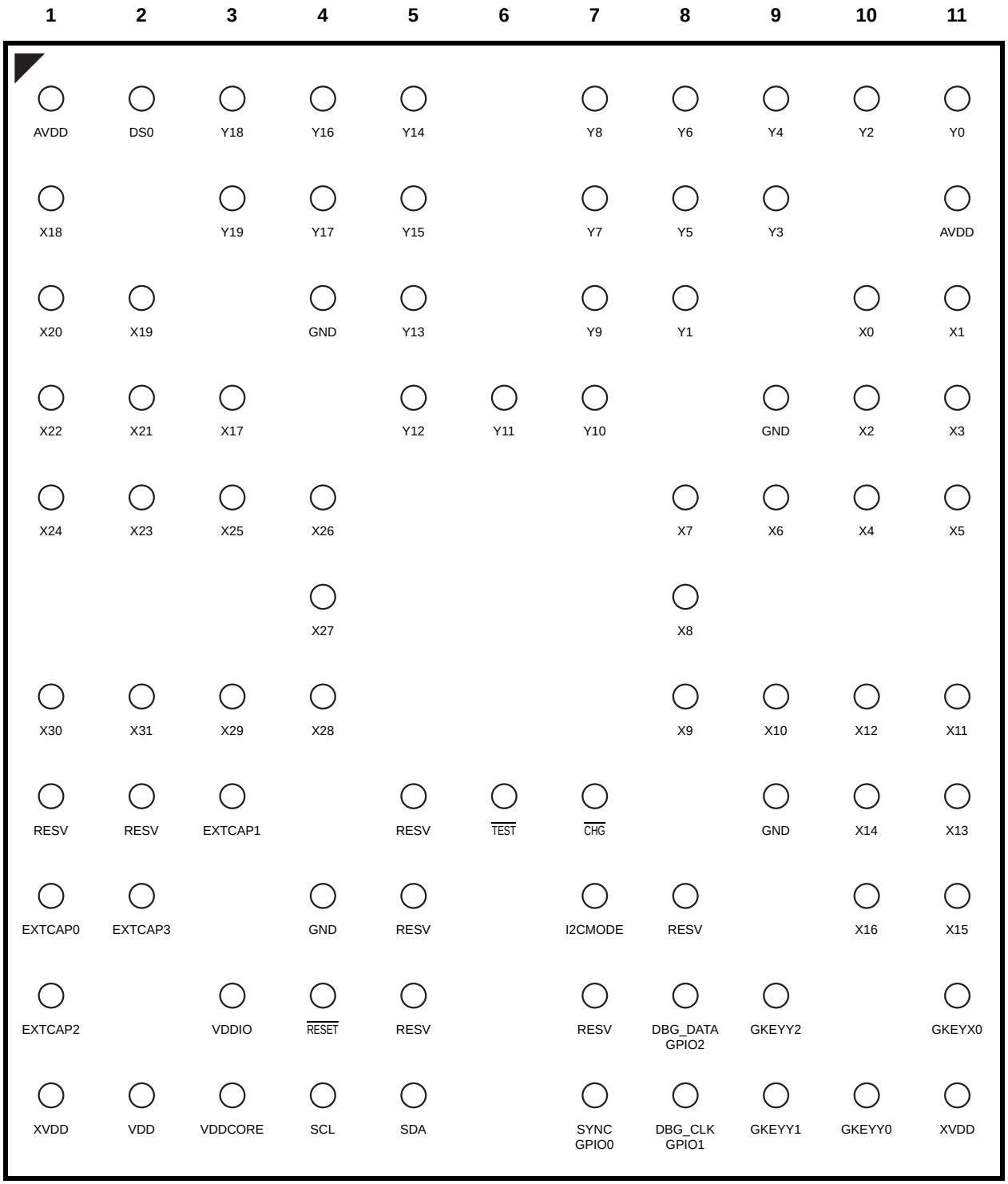
- –40°C to +85°C

Design Services

- Review of device configuration, stack-up and sensor patterns

PIN CONFIGURATION

88-ball UFBGA

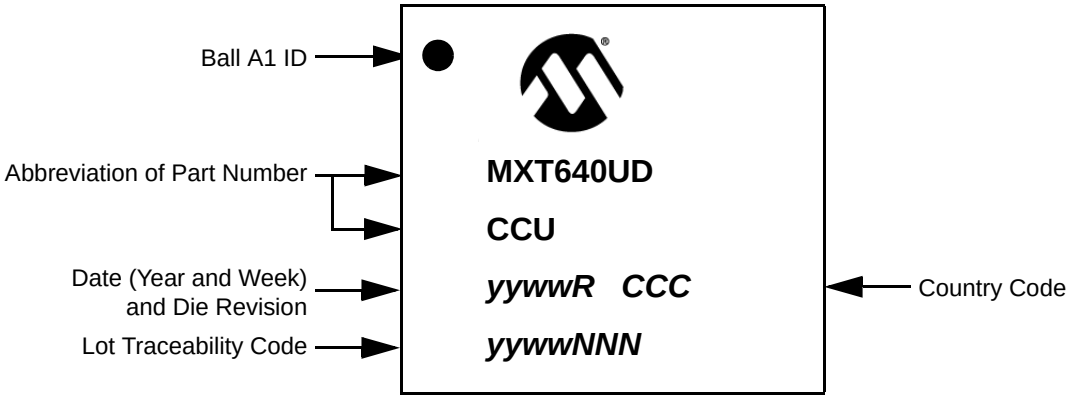


Top View

1.0 PACKAGING INFORMATION

1.1 Package Marking Information

1.1.1 88-BALL UFBGA



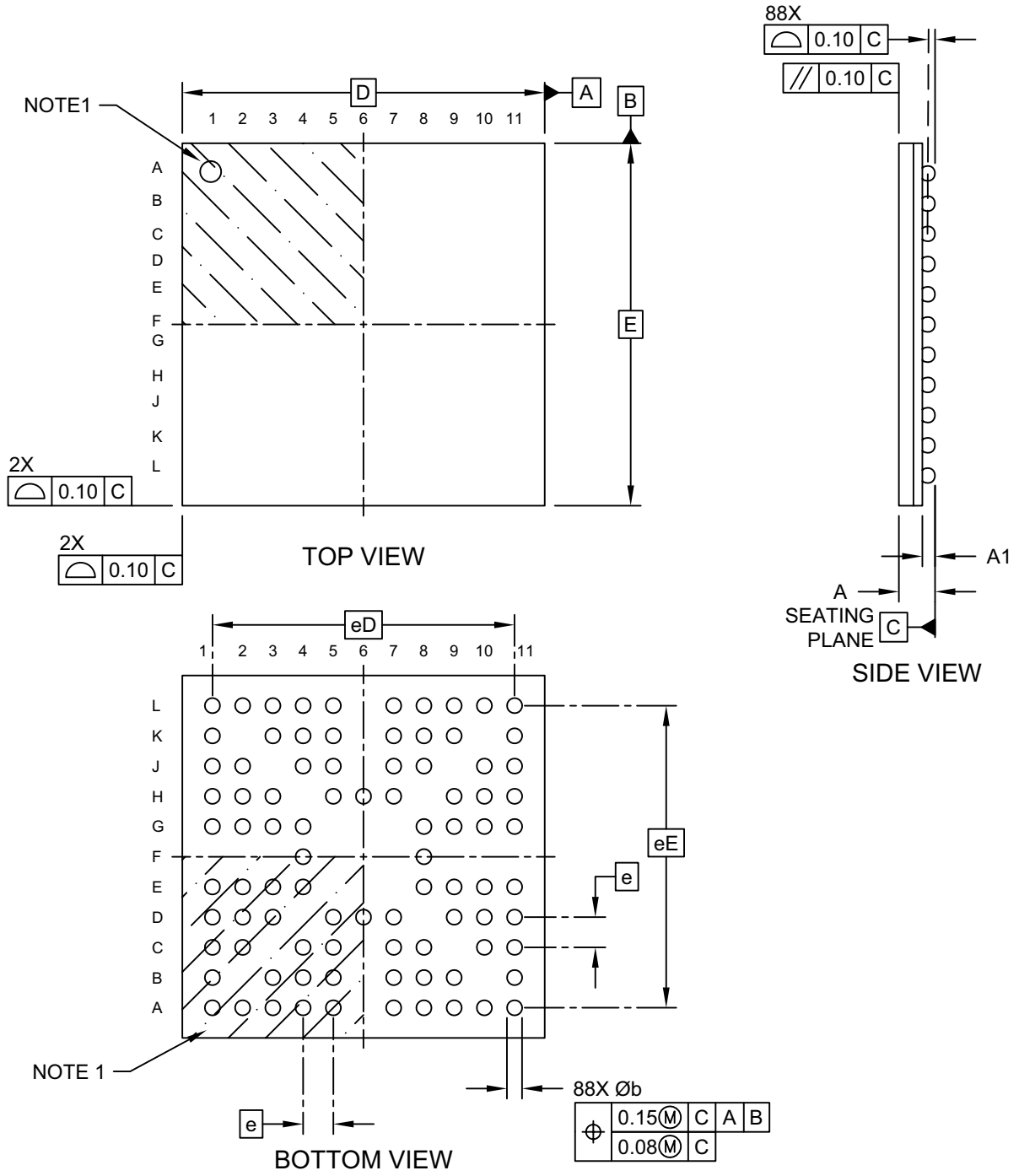
1.1.2 ORDERABLE PART NUMBERS

The product identification system for maXTouch devices is described in “Product Identification System” on page 9. That section also lists example part numbers for the device.

1.2 Package Details

88-Ball Ultra Thin Fine Pitch Ball Grid Array (BVB) - 6x6x0.6 mm Body [UFBGA]
Atmel Legacy Global Package Code CJM

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-21158 Rev A Sheet 1 of 2

88-Ball Ultra Thin Fine Pitch Ball Grid Array (BVB) - 6x6x0.6 mm Body [UFBGA]
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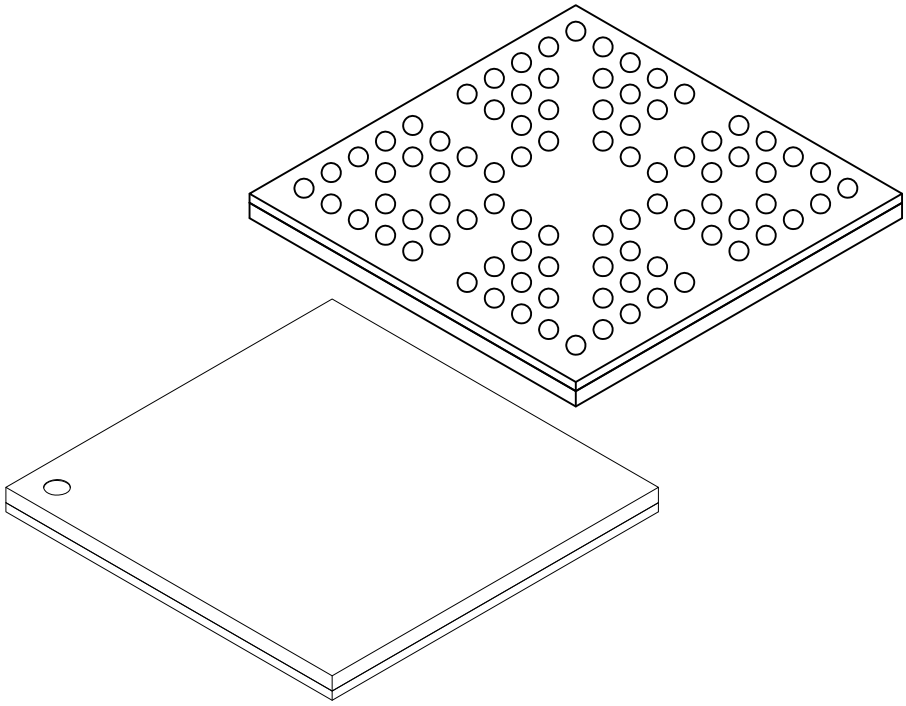

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N		88	
Pitch	e		0.50 BSC	
Overall Terminal Spacing	eD		5.00 BSC	
Overall Terminal Spacing	eE		5.00 BSC	
Overall Height	A	–	–	0.60
Standoff	A1	0.11	–	0.21
Overall Length	D		6.00 BSC	
Overall Width	E		6.00 BSC	
Terminal Diameter	b	0.22	0.25	0.28

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

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88-Ball Ultra Thin Fine Pitch Ball Grid Array (BVB) - 6x6x0.6 mm Body [UFBGA]
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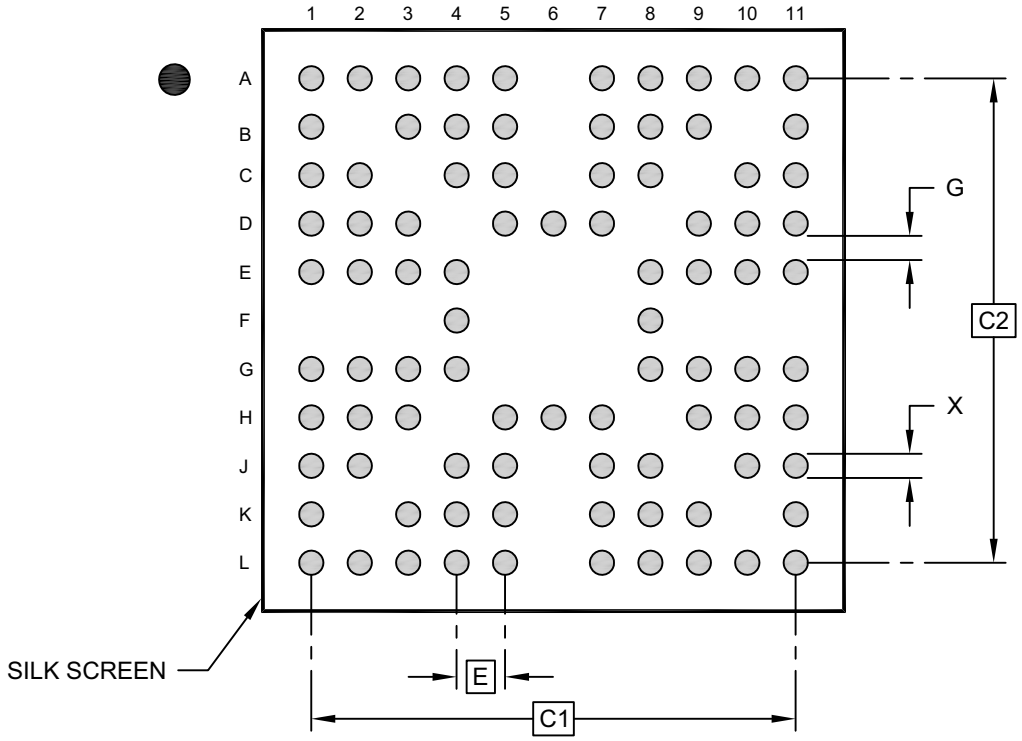

RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Overall Contact Pitch	C1	5.00 BSC		
Overall Contact Pitch	C2	5.00 BSC		
Contact Pad Diameter	X			0.28
Contact Pad to Contact Pad	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-23158 Rev A

APPENDIX A: REVISION HISTORY

Revision A (June 2021)

Initial edition for firmware revision 1.0.AA – Release

Revision B (November 2021)

Updated for firmware revision 1.0.AB – Release

PRODUCT IDENTIFICATION SYSTEM

The table below gives details on the product identification system for maXTouch devices. See "Orderable Part Numbers" below for example part numbers for the mXT640UD-CCU001.

To order or obtain information, for example on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	–XXX	[X]	[X]	[XXX]
Device	Package	Temperature Range	Tape and Reel Option	Pattern

Device:	Base device name		
Package:	CC	=	UFBGA (Ultra Thin Fine-pitch Ball Grid Array)
	C2	=	UFBGA (Ultra Thin Fine-pitch Ball Grid Array)
	NH	=	UFBGA (Ultra Thin Fine-pitch Ball Grid Array)
	C4	=	X1FBGA (Extra Thin Fine-pitch Ball Grid Array)
	MA	=	XQFN (Super Thin Quad Flat No Lead Sawn)
	MA5	=	XQFN (Super Thin Quad Flat No Lead Sawn)
Temperature Range:	U	=	–40°C to +85°C (Grade 3)
	T	=	–40°C to +85°C (Grade 3)
	B	=	–40°C to +105°C (Grade 2)
Tape and Reel Option:	*Blank*	=	Standard Packaging (Tube or Tray)
	R	=	Tape and Reel (1)
Pattern:	Extension, QTP, SQTP, Code or Special Requirements (Blank Otherwise)		

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. See "Orderable Part Numbers" below or check with your Microchip Sales Office for package availability with the Tape and Reel option.

Orderable Part Numbers

Orderable Part Number	Firmware Revision	Description
ATMXT640UD-CCU001 (Supplied in trays)	1.0.AB	88-ball UFBGA 6 × 6 × 0.6 mm, RoHS compliant Industrial grade; not suitable for automotive characterization
ATMXT640UD-CCUR001 (Supplied in tape and reel)		

NOTES:

Note the following details of the code protection feature on Microchip products:

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- Microchip believes that its family of products is secure when used in the intended manner, within operating specifications, and under normal conditions.
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